Wi-Fi[®]/ Bluetooth[®] Modules



Wi-Fi® modules

Type 1FX

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PN: LBWA1KL1FX-875

CYW43364 Chipset 6.95 x 5.15 x 1.1mm FCC/IC/CE*/Japan Certified





6.802.11 b/g/n

Wi-Fi® + Bluetooth® modules



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Type 1DX

PN: LBEE5KL1DX-883

CYW4343W Chipset 6.95 x 5.15 x 1.1 mm FCC/IC/CE*/Japan Certified





6802.11 b/g/n + Bluetooth® 4.2

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Type 1LV

PN: LBEE59B1LV-278 CYW43012 Chipset 10.0 x 7.2 x 1.4 mm





6802.11 a/b/g/n/ac + Bluetooth® 5.0

(It only supports 20MHz channel bandwidth)



Type 1MW

PN: LBEH5HY1MW-230

CYW43455 Chipset 7.9 x 7.3 x 1.1 mm FCC/IC/CE*/Japan Certified





6802.11 a/b/g/n/ac + Bluetooth® 5.0

Type 1CX

PN: LBEH5UL1CX-887 CYW4356 Chipset 11.5 x 8.8 x 1.0 mm







6802.11 a/b/g/n/ac + Bluetooth® 5.0



Type 1VA PN: LBEE5XV1VA-495

CYW88359 Chipset 11.4 x 8.9 x 1.4 mm FCC/IC/CE*/Japan Certified







6802.11 a/b/g/n/ac + Bluetooth 4.2

*Conducted results for CE Marking Conformity Assessment Procedures are available

Wi-Fi® MCU Modules



ElectricImp modules

Type 1GC/imp005

PN: LBWA1UZ1GC-958 PN: LBWA1UZ1GC-901 (Imp005) CYW43907 Chipset

10.0 x 10.0 x 1.3 mm





WICED, ElectricImp FCC/IC/CE* Reference Certified

6802.11 a/b/g/n + Ethernet + ARM Cortex- R4

Type 1MD/imp004m PN: LBEE5ZZ1MD-011

CYW43438+STM Chipset 21.0 x 17.5 x 2.3 mm



ElectricImp FCC/IC/CE*/Japan Certified

6802.11 b/g/n + Bluetooth® 4.1 + ARM Cortex- M4

electric imp

Type 1CD/imp003 PN:LBWA1ZV1CD-716

CYW43362+STM Chipset 10.0 x 7.9 x 1.25 mm





ElectricImp FCC/IC/CE* Reference Certified

> 6.802.11 b/g/n + ARM Cortex-M4

Ayla modules

Type 1LD

PN: LBEE5PA1LD-005 PN: LBEE5PA1LD-222(Ayla) CYW43438+STM Chipset

8.9 x 7.8 x 1.2 mm





WICED, Ayla FCC/IC/CE */Japan Certified

6802.11 b/g/n + Bluetooth® 4.2 + ARM Cortex-M4



Type 1AD

PN: LBWA1CS1AD-806

CYW4390 Chipset 9.4 x 8.9 x 1.2 mm





Ayla FCC/IC/CE* Reference Certified

6.802.11 b/g/n

+ ARM Cortex-M3



Wi-Fi® MCU Modules



Wi-Fi/BT MCU modules

Type 1QP

PN: LBEE5WQ1QP-276 CYW43907+CYW20707 Chipset 11.0 x 11.0 x 1.2 mm





WICED

6802.11 a/b/g/n + Bluetooth® 5.0 + ARM Cortex- R4

Type 1QX

PN: LBEE5WQ1QX-277 CYW54907+CYW20707 Chipset 11.0 x 11.0 x 1.2 mm





WICED

6802.11 a/b/g/n + Bluetooth® 5.0 + ARM Cortex- R4

Wi-Fi MCU modules

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Type 1PS

PN: LBWA1UZ1PS-241 CYW54907 Chipset 10.0 x 10.0 x 1.3 mm





WICED

#802.11 a/b/g/n/ac + Ethernet + ARM Cortex- R4



CYW43438+STM Chipset 21.0 x 17.5 x 2.3 mm



WICED FCC/IC/CE*/Japan Certified

6802.11 b/g/n + ARM Cortex- M4



Built-in Cloud Agent

**Available through Distribution Channels



*Conducted results for CE Marking Conformity Assessment Procedures are available

Bluetooth®/ BLE/ 802.15.4 Modules



Type 1PA
PN: LBCA1KU1PA-245
CYW20719 Chipset
5.9 x 5.1 x 1.17mm





Bluetooth/BLE WICED Studio

Bluetooth® 5.0

Type 1WA
PN: LBCA1KU1WA
CYW20721 Chipset
5.9 x 5.1 x 1.17mm





Bluetooth/BLE WICED Studio

Bluetooth® 5.0

Type 1GR

PN: LBCA1ZZ1GR-084 CYW20736 chipset 9.0 x 7.0 x 1.2mm





BLE WICED Studio FCC/IC/CE*/Japan Certified

Bluetooth® 4.1

*Conducted results for CE Marking Conformity Assessment Procedures are available